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Title: Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-1182-00	By: Lynn Johnson	Current Rev: 0A	Date: 8/7/2012
Assemblies Covered: R2000GZ/GL (786-1182-00)			



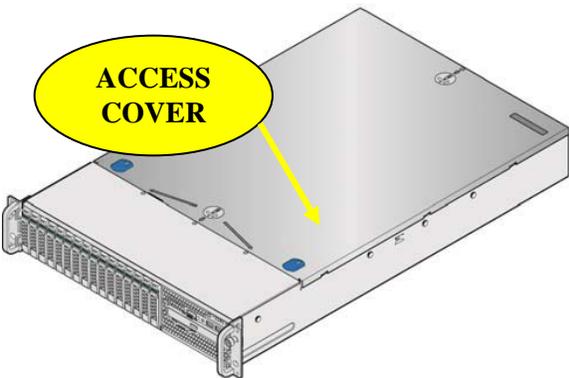
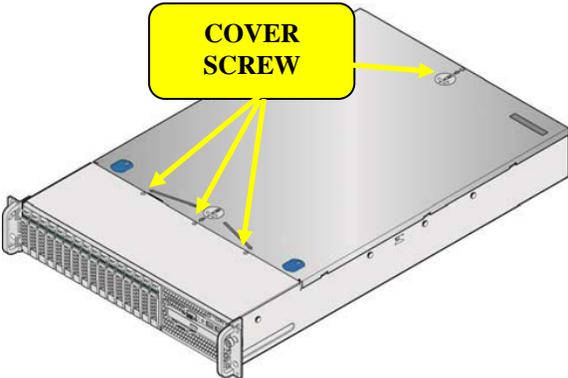
Revision	Date	ECO #	Revised By	Description of Changes
0A	08/21/2012	E02851	Lynn Johnson	Initial Release

Tools Required:

- #2 Phillips Screwdriver
- #1 Phillips Screwdriver
- Needle nose Pliers

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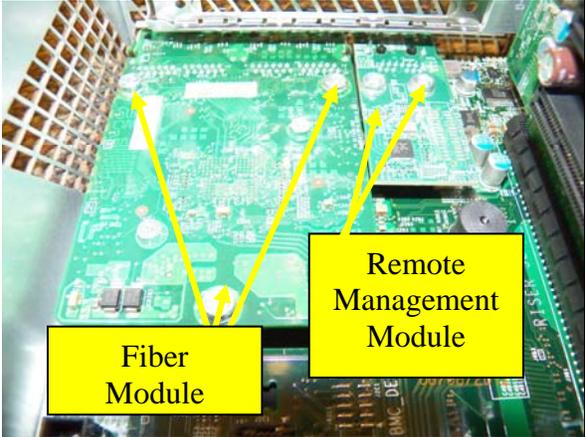
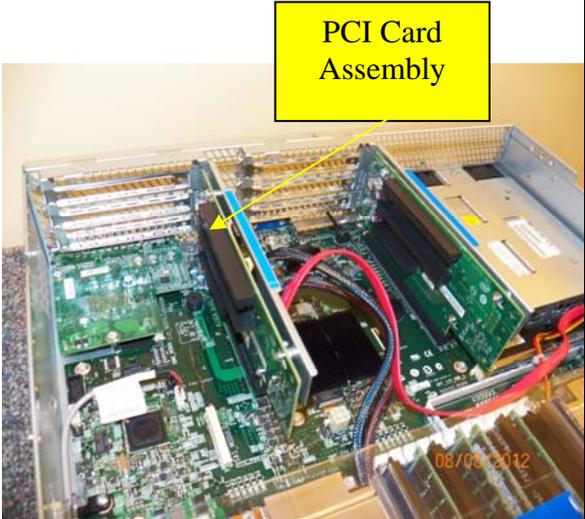
NOTE : Disconnect any AC Power Cords attached to the power supplies before disassembly of the unit.

1.	<p>Removal of the top access cover requires a #2 Philips screwdriver.</p> <ol style="list-style-type: none"> a. Remove the four cover screws. b. Slide the top cover towards the rear of the chassis about an inch. c. Remove access cover by lifting it up. d. Remove any labels from the chassis and access cover. e. Discard Sheet Metal Cover, Cover Screw, and Labels in the appropriate Recycling Bin. 	
1.		

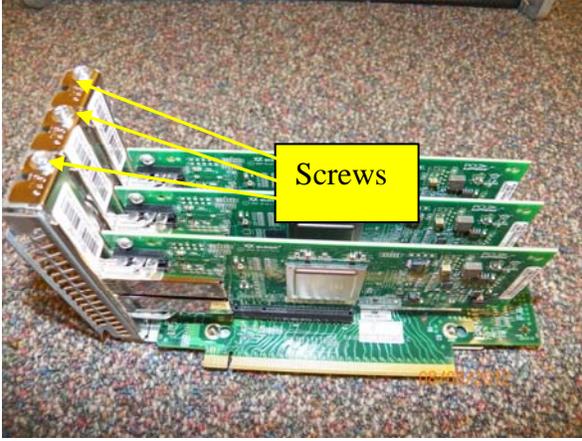
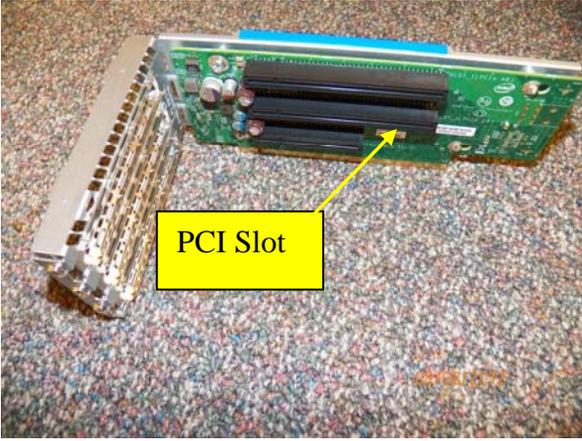
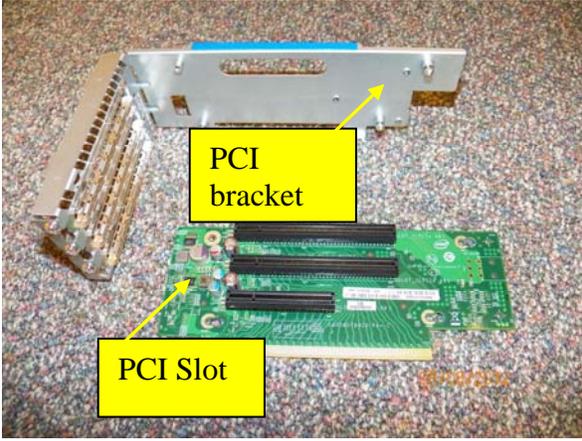
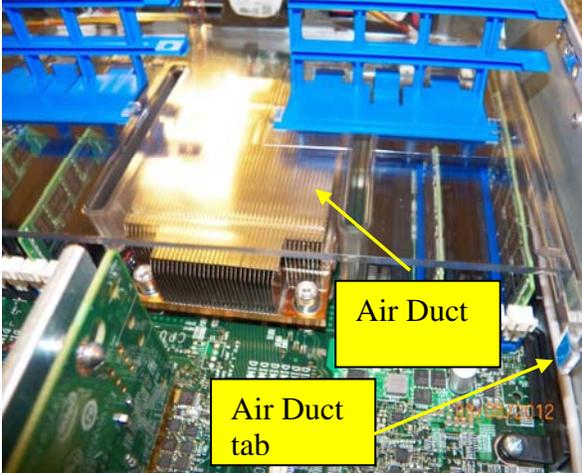
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1.		
2.	<p>Removal of the bezel brackets (if present) requires a #2 Phillips screw driver.</p> <ol style="list-style-type: none"> a. Remove the two (2) screws securing each bezel bracket to the chassis, and pull the bracket off the chassis. b. Discard Bezel Brackets and screws in the appropriate Recycling Bin. 	

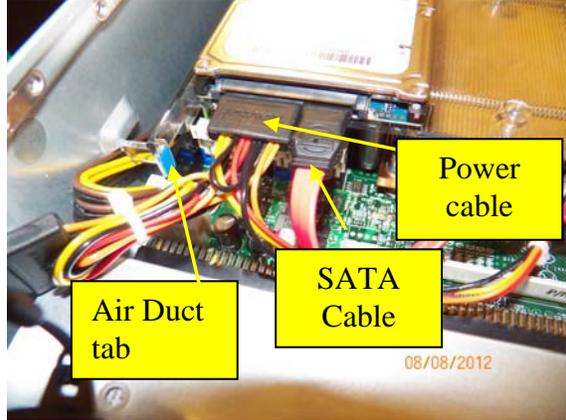
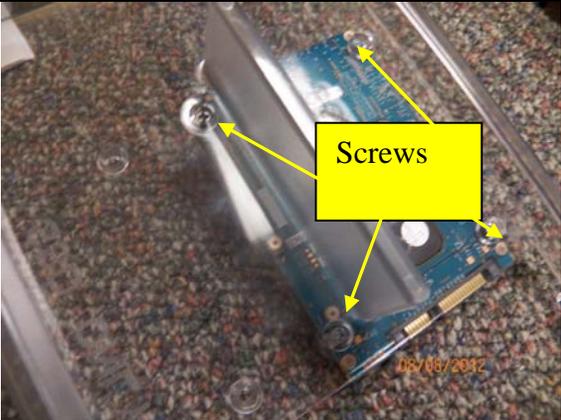
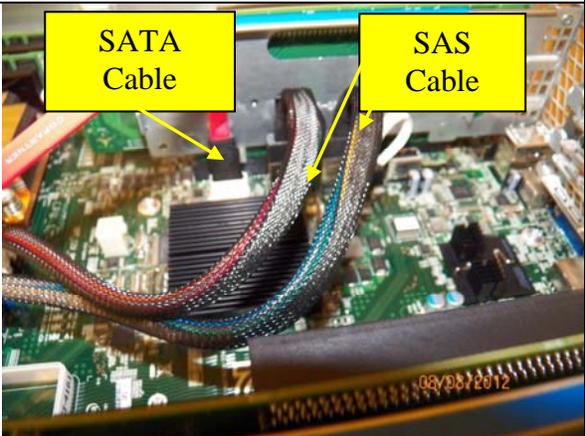
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<p>3.</p> <p>Removal of the Power Supply (ies) does not require any tools.</p> <ol style="list-style-type: none"> a. Press and hold the green button towards the power supply handle. b. Pull the supply straight out of the rear of the chassis. c. Discard the Power Supply (ies) in the appropriate Recycling Bin. 	
<p>4.</p> <p>Removal of the Remote Management Module and Fiber module requires a #2 Phillips Screw driver.</p> <ol style="list-style-type: none"> a. Remove the screws securing the Remote Management and Fiber module to the motherboard and pull the modules from the motherboard. b. Discard the Screws, the Remote Management Module, and the Fiber Module in the appropriate Recycling Bin. 	
<p>5.</p> <p>Removal of the PCI card assembly does not require any tools.</p> <ol style="list-style-type: none"> a. Remove the PCI card assembly by lifting it straight out of the chassis. 	

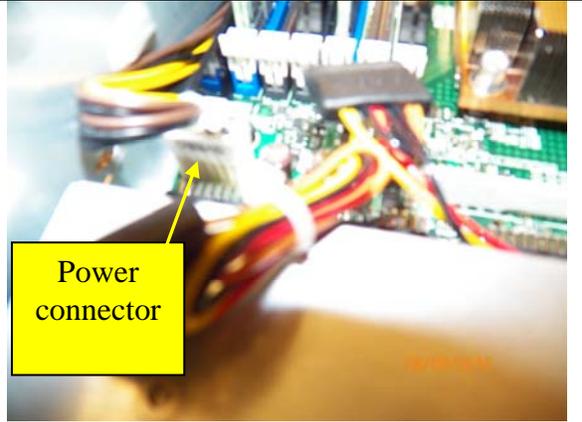
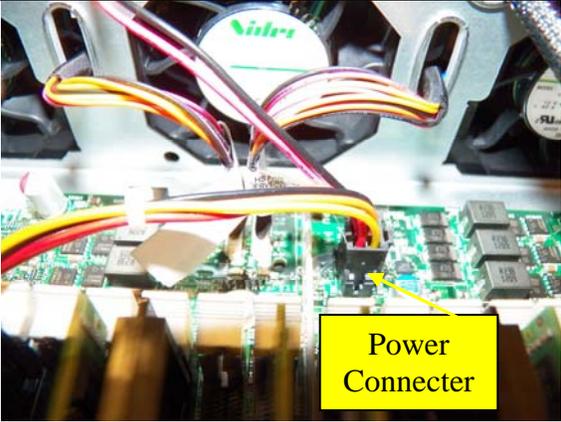
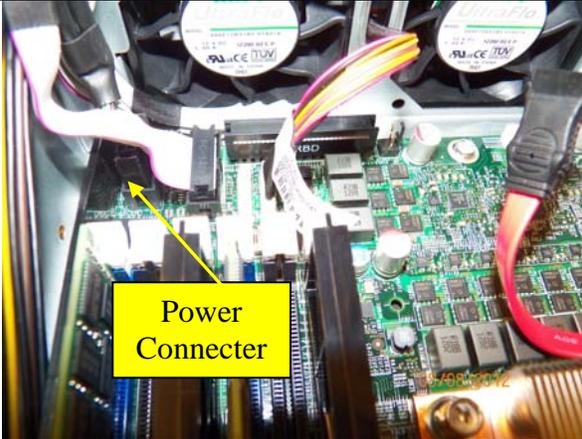
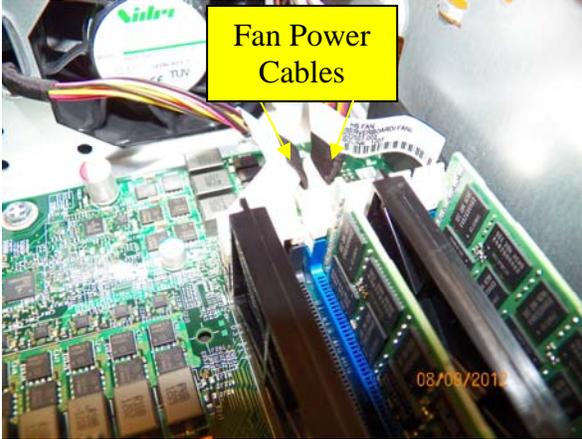
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6.	<p>Removal of the PCI card (if installed) requires a #2 Phillips screw driver.</p> <ol style="list-style-type: none"> a. Remove the screw securing the PCI cards to the bracket, and pull the PCI cards out away from the riser. b. Remove the screw connecting the PCI slot to the PCI bracket. c. Discard the PCI card, PCI slot, PCI bracket and screws in the appropriate Recycling Bin. 	
6.		
7.	<p>Removal of the Air Duct does not require any tools.</p> <ol style="list-style-type: none"> a) Remove the Air Duct by pressing the Air Duct tabs inward and pulling it straight up and out of the chassis. b. Discard the Air Duct in the appropriate Recycling Bin. 	

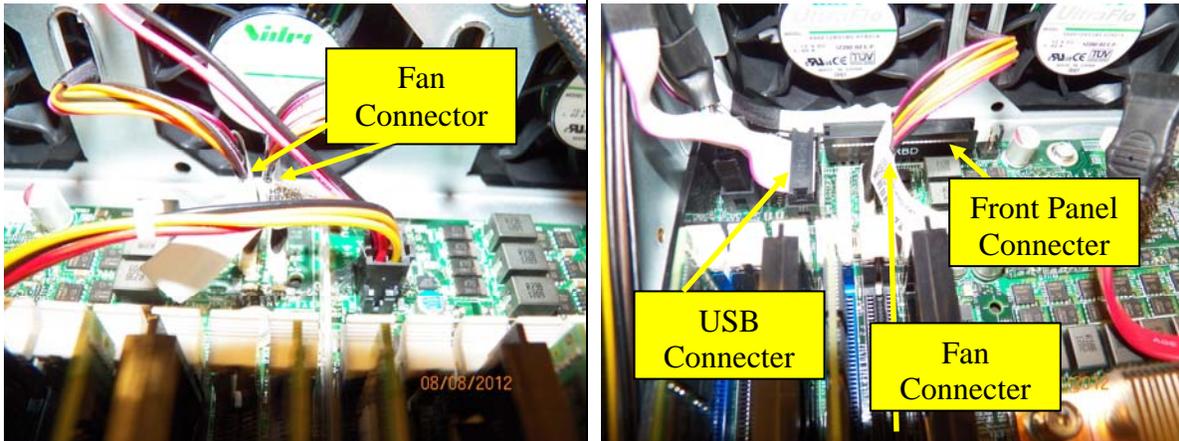
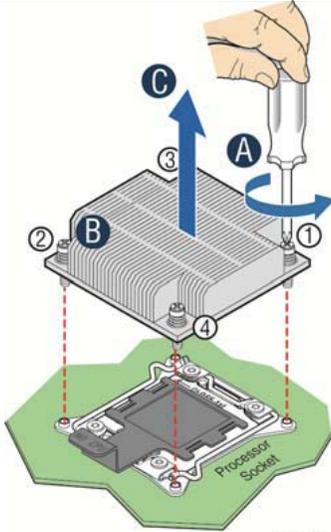
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8.	<p>Removal of the SSD (if present) requires a #2 Phillips screwdriver.</p> <ol style="list-style-type: none"> a. Disconnect the power cable from the SSD. b. Disconnect the SATA cable from the SSD. c. Remove the four screws that mounts the SSD to the air duct. d. Discard the screws, the power cable, the SATA cable, and the SSD in the appropriate Recycling Bin. 	
8.		
9.	<p>Removal of the SAS Cables and the SATA Cable do not require any tools.</p> <ol style="list-style-type: none"> a. Remove the two (2) SAS Cables and the SATA Cable from the motherboard. b. Discard the two (2) SAS Cables and the SATA Cable in the appropriate Recycling Bin. 	

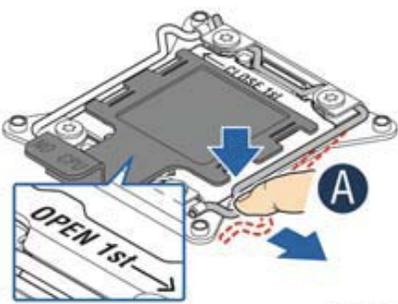
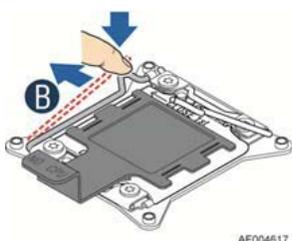
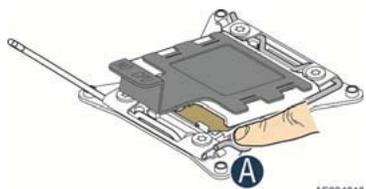
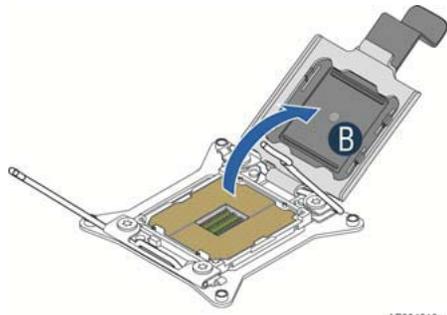
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10.	<p>Removal of the Power Cables does not require any tools.</p> <ol style="list-style-type: none"> a. Disconnect the three (3) Power connectors from the motherboard. b. Pull the Power Cables straight up to remove. 	
10.		
11.	<p>Removal of the fan power connectors, front panel connector, USB connector, and HSBP I2C connector does not require any tools.</p> <ol style="list-style-type: none"> a. Disconnect the five (5) fan power cables from the motherboard. b. Disconnect the USB cables from the motherboard. c. Disconnect the HSBP cable from the motherboard. 	

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11.	
12.	<p>Removal of the CPU Heatsinks requires a #2 Phillips screwdriver.</p> <ol style="list-style-type: none"> a. Start loosening the four (4) screws on the heat sink two turns at a time in the order shown in the picture below. b. Once all screws are fully out, lift the heat sinks out of the chassis. c. Discard the Heat sinks in the appropriate Recycling Bin.  <p style="text-align: right; font-size: small;">AF004621</p>

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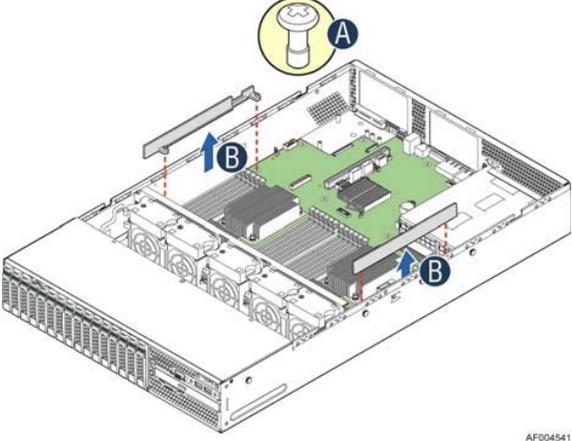
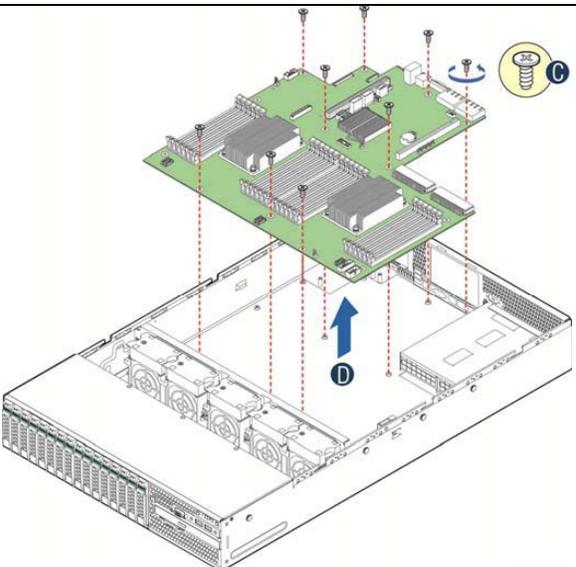
12.	<p>Removal of the processor does not require any tools.</p> <ol style="list-style-type: none"> a. Open the socket lever. Push down the lever handle on the OPEN 1st side and away from the socket to release it (see letter “A”). b. Repeat the steps to release the lever on the other side (see letter “B”). c. Open the Load Plate. Press the locking lever slightly to raise the load plate (see letter “A”). Open the load plate all the way (see letter “B”). Remove the Processor. d. Discard the Processor in the appropriate Recycling Bin. 	 <p style="text-align: right;">AF004616</p>
12.	 <p style="text-align: right;">AF004617</p>	 <p style="text-align: right;">AF004618</p>
12.	 <p style="text-align: right;">AF004619</p>	

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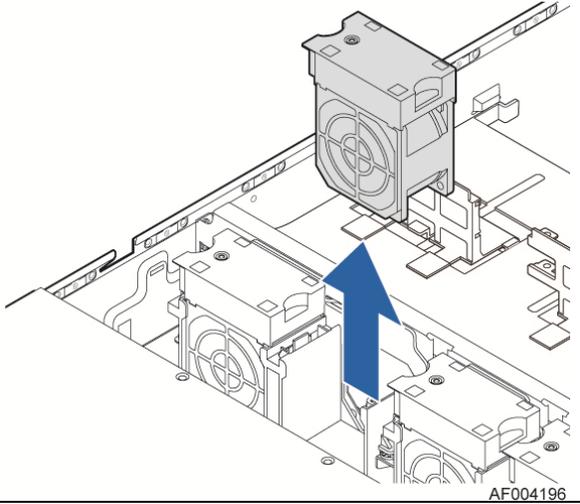
13. Removal of the Memory DIMMs, Memory blanks, and Lithium Battery from the motherboard do not require any tools.
- a. Remove each of the Memory DIMMs by pushing down and out on the two latches, one on each end of the DIMM connector. Lift memory DIMM straight out to remove.
 - b. Put a piece of scotch tape on both sides of the battery and remove the coin style Lithium Battery.
 - c. Discard the Memory DIMMs and Lithium Battery in the appropriate Recycling Bin.**
- *** CAUTION *****
- Care should be observed when disposing of the battery to avoid shorting it!**



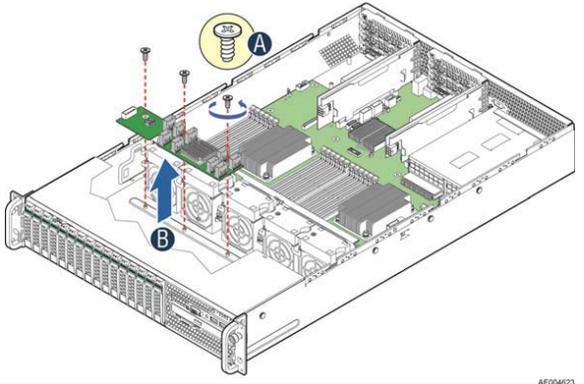
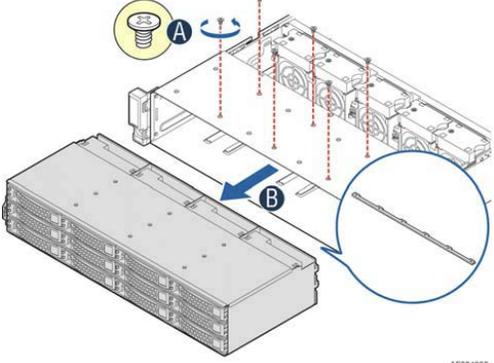
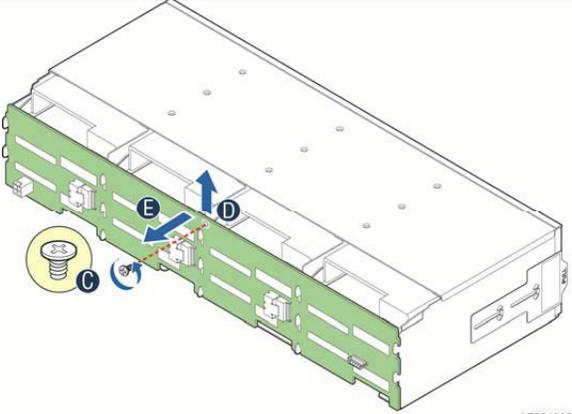
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<p>14. Removal of the motherboard requires a #2 Phillips screw driver.</p> <ol style="list-style-type: none"> a. Disconnect all cables from the motherboard. b. If applicable, remove the four screws to release the air duct side wall (see letter "A"). Lift the air duct side wall straight up to remove from the motherboard (see letter "B"). c. Remove the nine screws from the server board (see letter "C"). Lift the board from the server system ("D"). d. Discard the Motherboard in the appropriate Recycling Bin. 	 <p style="text-align: right; font-size: small;">AF004541</p>
<p>14.</p>	 <p style="text-align: right; font-size: small;">AF004339</p>

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15.	<p>Removal of the Fans do not require any tools.</p> <ol style="list-style-type: none"> a. Pull the five (5) system fans straight up to remove it from the fan holder. b. Discard the Fans in the appropriate Recycling Bin. 	 <p style="text-align: right; font-size: small;">AF004196</p>
16.		
16.	<p>If applicable, removal of the RAID expander requires a #2 Phillips screw driver.</p> <ol style="list-style-type: none"> a. Disconnect all cables from the expander. b. Remove the three screws that mount the expander to the chassis (see letter "A"). c. Lift the RAID expander card straight up. (see letter "B"). d. Discard the cables, screws, and RAID expander card in the appropriate Recycling Bin. 	

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16.		
17.	<p>If applicable, remove the 3.5" Hard Drive Backplane requires a #2 Phillips screw driver.</p> <ol style="list-style-type: none"> a. Disconnect all cables from the backplane. b. Remove all hot-swap drive carriers, regardless of whether or not a drive is installed in the carrier. Remove the six screws to release the hard drive cage (see letter "A"). c. Slide the hard drive cage out of the server chassis, the clip will fall out automatically (see letter "B"). 	
17.	<ol style="list-style-type: none"> d. Remove the screw at the rear of the backplane (see letter "C"). e. Pull up the backplane (see letter "D"). Remove the backplane from the server chassis (see letter "E"). f. Discard the cables, the hot-swap drive cage, the screws, and the backplane in the appropriate Recycling Bin. 	

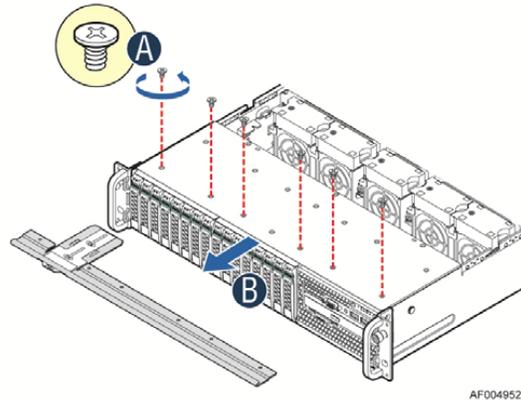
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0ADate:
8/7/2012

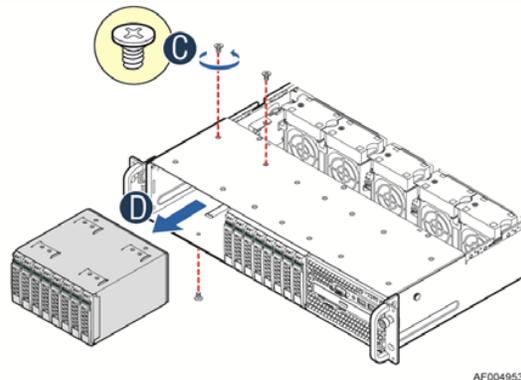
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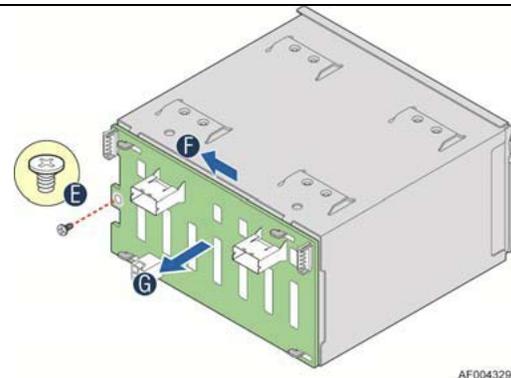
18. If applicable, remove the 2.5" Hard Drive Backplane requires a #2 Phillips screw driver.
- Disconnect all cables from the backplane.
 - Remove all hot-swap drive carriers, regardless of whether or not a drive is installed in the carrier. Remove the six screws to release the stiffener (see letter "A").
 - Slide the stiffener cage out of the server chassis (see letter "B").



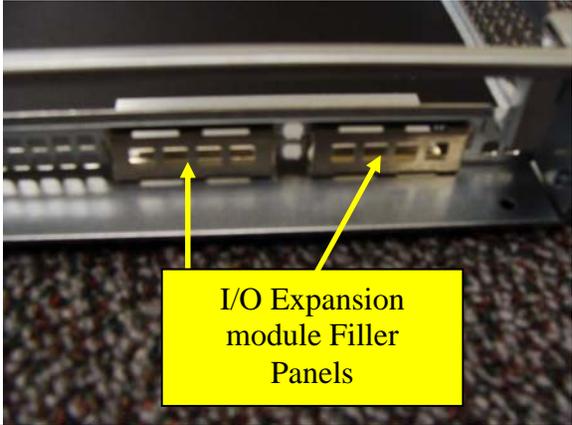
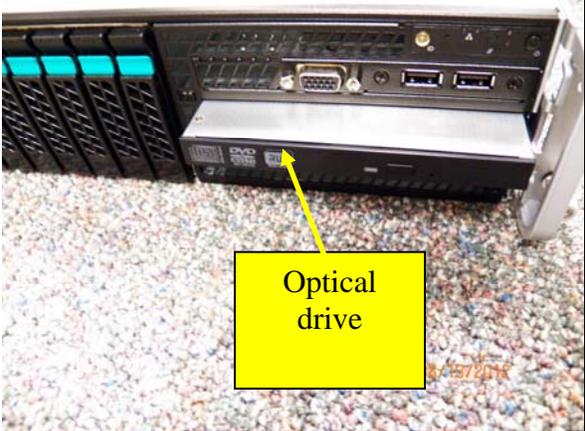
- Remove the three screws to release the hard drive cage (see letter "C").
- Slide the hard drive cage out of the server chassis (see letter "D").
- Remove the screw from the backplane board (see letter "E").
- Hold the backplane board only by the edges and slide the backplane board in the direction shown to release it (see letter "F"). Remove the backplane board from the four hooks and pull out of the hard drive cage (see letter "G").



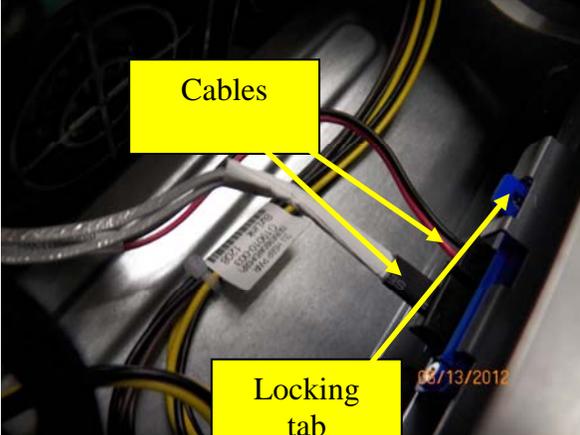
- h. Discard the cables, the hot-swap drive cage, the screws, and the backplane board in the appropriate Recycling Bin.**



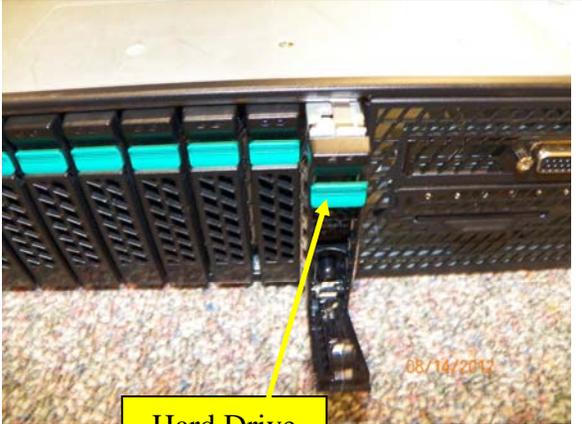
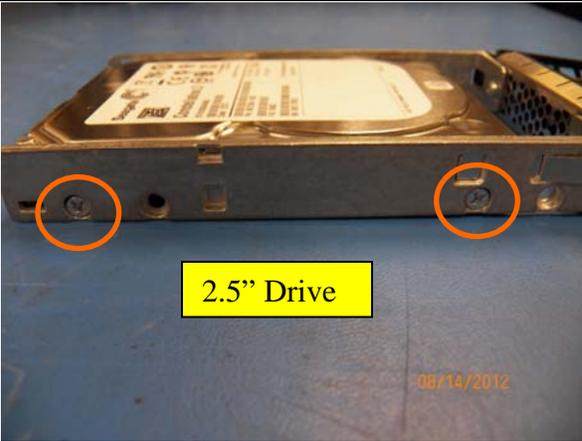
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17.	<p>If applicable, removal of any I/O Expansion Module Filler Panels does not require any tools.</p> <ol style="list-style-type: none"> a. Squeeze the sides of the I/O expansion module filler panel(s) to disengage it from the server system back panel and remove it. b. Discard the filler panels in the appropriate Recycling Bin. 	
18.	<p>Removal of the Optical Drive (if present) requires a #1 Phillips screw driver any tools.</p> <ol style="list-style-type: none"> a. Remove cables from the optical drive, press the locking tab at the rear of the optical drive just above the backplane, and pull the drive straight out of the chassis. b. Remove the two (2) screws from the locking tab. c. Discard the cables, optical drive, locking tab, and the screws in the appropriate Recycling Bin. 	

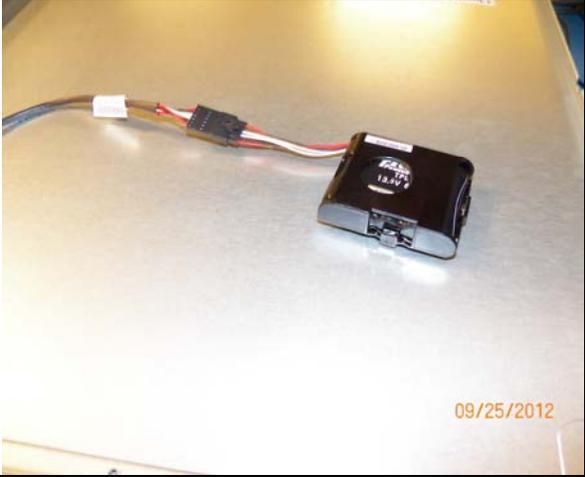
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18.	 <p>Cables</p> <p>Locking tab</p>	 <p>Screws</p>
19.	<p>Removal of the 2.5" Hard Drive (s) requires a #1 Phillips screw driver and the removal of the 3.5" Hard Drive (s) requires #2 Phillips screw driver.</p> <ol style="list-style-type: none"> a. Press the tab on the front of the drive carrier, and pull the drive straight out of the chassis. b. Remove the four (4) screws securing the drive to the carrier (two on each side for the 3.5in drive and 4 on the 2.5in drive). (Repeat for each drive installed) c. Discard the Hard Drive(s), Carriers, and screws in the appropriate Recycling Bin. 	 <p>Hard Drive Carrier</p>

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19.	 <p style="text-align: center;">3.5" Drive</p>	 <p style="text-align: center;">Hard Drive Carrier</p>
19.	 <p style="text-align: center;">2.5" Drive</p>	
20.	<p>Removal of the Super cap (if present) does not require any tools.</p> <ol style="list-style-type: none"> a. Remove cables from the super cap, press the locking tab at the top of the super cap, and pull the super cap straight out of the chassis. b. Remove the cables from the super cap and the RAID controller. c. Discard the cables, and the super cap in the appropriate Recycling Bin. 	

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21.	<p>Removal of the BBU (if present) does not require any tools.</p> <ol style="list-style-type: none"> a. Remove cables from the BBU, press the locking tab at the top of the BBU, and pull the BBU straight out of the chassis. b. Remove the cables from the the RAID controller. c. Discard the cables, and the BBU in the appropriate Recycling Bin. 	
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Fully Disassembled Unit

DISCARD THE FULLY DISASSEMBLED UNIT IN THE APPROPRIATE RECYCLE BIN.

Recycling/Material Code	Important Information
Material /Components, which must be removed and treated separately	
Lithium Battery	Battery free of hazardous substances, installed in socket on the motherboard
Printed circuit boards	Motherboard, DIMMs, PCI card, PCI riser, Power Supply, Backplane, RAID IO Module, Power Distribution Board, IO Expansion

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	Module, Remote Management Module, , & Front Panel Control Board
Disk Drives	Mounted on disk carrier
Material /Components, which can disturb certain recycling processes	
Copper	Fansink
Material /Components, through which benefits can normally be achieved	
Cold Rolled Steel	Fixed cover, PCI bracket, & chassis
* ABS	Bezel, Control Panel Bezel, Cable Guide, Power Distribution Board Cover, Fan Assembly, & Air Duct
Cables	Distributed in device & power cord
Fans	Fan Assembly
Special notes	
* Flame retardant of plastics do not contain PBB and PBDE.	

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Annex A

Producer:	<company name, other on addressing the producer>
Scope of information sheet:	< product category as in Annex IA of WEEE Directive, or type of equipment as in Annex 1B of WEEE Directive, or producer's Product Family, or single products identified by brand and model name >

Component or Material	Remarks / Location
Battery (internal *) containing Mercury (Hg)/ NiCad/Lithium/ Other	Lithium battery ↓ located on the motherboard
Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	NONE
Mercury (Hg) in other applications**	NONE
Cadmium**	NONE
Gas discharge lamps	NONE
Plastic containing brominated flame retardants other than in Printed Circuit Assemblies ***	NONE
Liquid Crystal Displays with a surface greater than 100 cm ²	NONE
Capacitors with PCB's	NONE
Capacitors with substances of concern**** + height > 25 mm, diameter > 25 mm or proportionately similar volume	NONE
Asbestos	NONE
Refractory ceramic fibres	NONE
Radio-active substances	NONE
Beryllium Oxide	NONE
Other forms of Beryllium	BE-CU in some connector contacts ↓
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC).	NONE
Components with pressurised gas which need special attention (Pressure > 1,5 bar) *****	NONE
Liquids ***** if volume > 10 cl (or equivalence in weight, e.g. for PCB, oil...)	NONE
Mechanical components that store mechanical energy (i.e. springs) or equivalent parts which need special attention ***** (diameter > 10 mm and height > 25 mm or proportionally similar volume and expanding)	NONE
PBDE (deca- & octa-BDE) and Perfluorocatane sulfantes (PFOS) in Directive 2006/122/EC	NONE

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Title: Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-1182-00	By: Lynn Johnson	Current Rev: 0A	Date: 8/7/2012
Assemblies Covered: R2000GZ/GL (786-1182-00)			

↓ = arrow indicates the need for the location of the compartment/ substances within the product. When the location of a substance/ components is requested, it is at part level, e.g. main board, housing etc

* Internal means that batteries can only be removed by opening the product by means of (a) tool(s).

** Substances are considered to be in the product if present above the levels specified in Commission Decision 2005/618/EC related to Directive 2002/95/(EC) (RoHS Directive) or if their use is permitted through exemptions in the Annex of Directive 2002/95(EC)

*** To be coherent with industry current standards and practices on tracking of plastic parts, Directive 2002/96 (EC) Annex II requirement is understood to focus on plastic parts that weight more than 25 g.

**** Substance of concern other than PCB, to be specified/ addressed further in the context of Directive 2002/96 (EC) Annex II national requirements and European developments

***** Needs of equivalent nature as those for maintenance, service manuals and installation for safety purposes.